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## **PACKAGING INFORMATION**

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	(3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CD54HC4094F3A	Active	Production	CDIP (J)   16	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC4094F3A
CD54HC4094F3A.A	Active	Production	CDIP (J)   16	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	CD54HC4094F3A
CD74HC4094DYYR	Active	Production	SOT-23-THIN (DYY)   16	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HJ4094
CD74HC4094DYYR.A	Active	Production	SOT-23-THIN (DYY)   16	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HJ4094
CD74HC4094E	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC4094E
CD74HC4094E.A	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HC4094E
CD74HC4094M	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	-55 to 125	HC4094M
CD74HC4094M96	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094M96.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094M96G3	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094M96G3.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094M96G4	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094M96G4.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094MT	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	-55 to 125	HC4094M
CD74HC4094NSR	Active	Production	SOP (NS)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094NSR.A	Active	Production	SOP (NS)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094NSRE4	Active	Production	SOP (NS)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4094M
CD74HC4094PW	Obsolete	Production	TSSOP (PW)   16	-	-	Call TI	Call TI	-55 to 125	HJ4094
CD74HC4094PWR	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 125	HJ4094
CD74HC4094PWR.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4094
CD74HC4094PWRE4	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4094
CD74HC4094PWRG4	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4094
CD74HC4094PWRG4.A	Active	Production	TSSOP (PW)   16	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4094
CD74HCT4094E	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT4094E
CD74HCT4094E.A	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT4094E
CD74HCT4094EE4	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	-55 to 125	CD74HCT4094E
CD74HCT4094M	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	-55 to 125	HCT4094M
CD74HCT4094M96	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-55 to 125	HCT4094M

## PACKAGE OPTION ADDENDUM

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Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
CD74HCT4094M96.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4094M

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## OTHER QUALIFIED VERSIONS OF CD54HC4094, CD74HC4094:

Catalog: CD74HC4094

Military: CD54HC4094

NOTE: Qualified Version Definitions:

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.



## **PACKAGE OPTION ADDENDUM**

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- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications